

Filename: PMP9621\_REVA\_bom.xls

Date: March 6, 2014

## PMP9621\_REVA BOM

COUNT	RefDes	Value	Description	SIZE	Part Number	MFR
1	C23	0.033uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C15	0.1uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
1	C32	0.33uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C10 C34	1000pF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C33	1uF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
1	C16	330pF	Capacitor, Ceramic, 50V, NPO, 10%	603	Std	Std
1	C37	6800pF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C14 C36	DNP	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C35	4.7uF	Capacitor, Ceramic, 16V, X7R, 15%	805	Std	TDK
1	C17	1uF	Capacitor, Ceramic, 100V, X7R, 15%	1206	Std	TDK
8	C2-9	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225MT	TDK
3	C26-28	22uF	Capacitor, Ceramic, 16V, X7R, 15%	1210	C3225X7R1C226MT	TDK
1	C1	220uF	Capacitor, Alum, 63V, ±20%	12.5x13.5mm	EEVFK1J221Q	Panasonic
2	C22 C38	470uF	Capacitor, Aluminum Polymer, 8mOhm, 5.7A	0.315 inch	6SEPC470MX	Sanyo
3	C11-13	820uF	Capacitor, Alum 23mOhms, 2.73A	0.630 inch	50 ZL 820uF M 16x20	Rubycon
1	J1	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	L1	3.3uH	Inductor, SMT, 7.22A, 10.4 milliohm	10.2x10mm	MSS1048-332NL	Coilcraft
1	L2	10uH	Inductor, 28A, 2.6 milliohm	1.1"x1.1"	SER2918H-103KL	Coilcraft
2	R6 R9	<b>2.2</b>	Resistor, Chip, 1/16-W, 5%	603	Std	Std
3	R8 R14 R16	0	Resistor, Chip, 1/16-W, 5%	603	Std	Std
1	R1	1 M	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R21	100	Resistor, Chip, 1%, 0603	603	Std	Std
1	R4	100k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R11 R15	10K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R18	13K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R2	1M	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R19	2.74k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R20	20.0k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R12	5.90k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R3	54.9k	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R22	549	Resistor, Chip, 1%, 0603	603	Std	Std
1	R17	97.6K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
3	R7 R10 R13	DNP	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R5	0	Resistor, Chip, 1/16W, 5%	805	Std	Std
1	J3	ED120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40"x0.35"	ED120/2DS	OST
1	J2	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27"x0.25"	ED555/2DS	OST
9	TP1-2 TP4-8 TP11-12	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 in	5000	Keystone
3	TP3 TP9-10	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 in	5001	Keystone
1	U1	TPS40170RGY	IC, 4.5V-60V Wide Input Sync Buck Controller	QFN-20	TPS40170RGY	TI
2	Q3-4	CSD18531Q5A	MOSFET, Nch, 60V, 4.4 milliohm	TDSON-8	CSD18531Q5A	Texas Instruments
2	Q1-2	CSD18537NQ5A	MOSFET, Nch, 60V, 13 milliohm	TDSON-8	CSD18537NQ5A	Texas Instruments
1	PWB	PMP6680 REV A				any

Add C38 by hand in the C21- C24 area

R6 & R9 updated in Test from zero to 2.2 ohms each

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